CY62256VN

256K (32K x 8) Static RAM

Features

- **Temperature Ranges**
  - **— Commercial: 0°C to 70°C**
  - **— Industrial: –40°C to 85°C**
  - **— Automotive-A: –40°C to 85°C**
  - **— Automotive-E: –40°C to 125°C**
- **Speed: 70 ns**
- **Low voltage range: 2.7V–3.6V**
- **Low active power and standby power**
- **Easy memory expansion with $\overline{CE}$ and $\overline{OE}$ features**
- **TTL-compatible inputs and outputs**
- **Automatic power-down when deselected**
- **CMOS for optimum speed/power**
- **Available in standard Pb-free and non Pb-free 28-lead (300-mil) narrow SOIC, 28-lead TSOP-I and 28-lead Reverse TSOP-I packages**

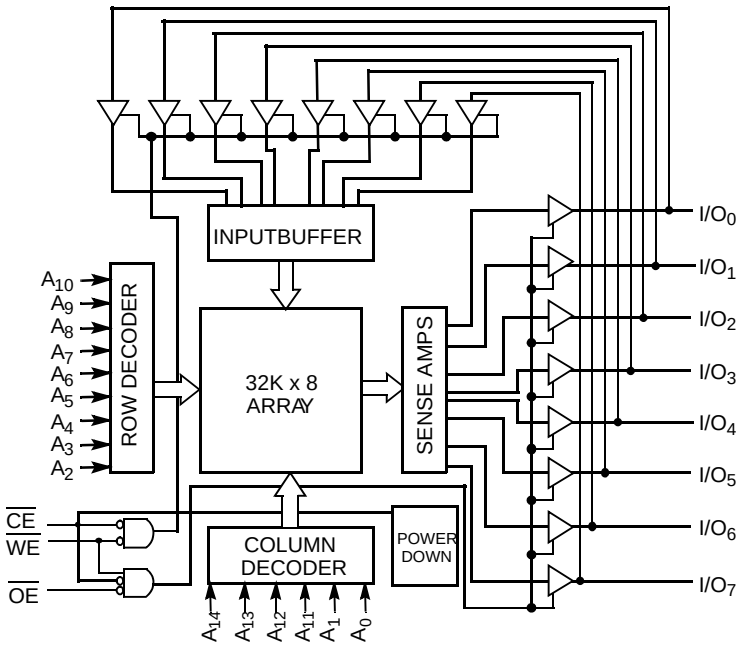
Functional Description[1]

The CY62256VN family is composed of two high-performance CMOS static RAM's organized as 32K words by 8 bits. Easy memory expansion is provided by an active LOW chip enable ($\overline{CE}$) and active LOW output enable ($\overline{OE}$) and tri-state drivers. These devices have an automatic power-down feature, reducing the power consumption by over 99% when deselected.

An active LOW write enable signal ($\overline{WE}$) controls the writing/reading operation of the memory. When $\overline{CE}$ and $\overline{WE}$ inputs are both LOW, data on the eight data input/output pins (I/O_0 through I/O_7) is written into the memory location addressed by the address present on the address pins (A_0 through A_{14}). Reading the device is accomplished by selecting the device and enabling the outputs, $\overline{CE}$ and $\overline{OE}$ active LOW, while $\overline{WE}$ remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins are present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and write enable ($\overline{WE}$) is HIGH.

Logic Block Diagram



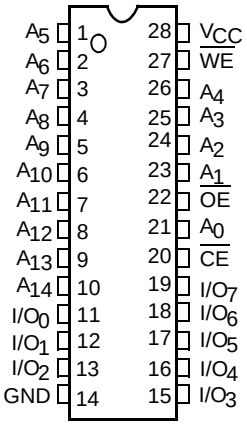
Note:
1. For best practice recommendations, please refer to the Cypress application note "System Design Guidelines" on http://www.cypress.com.

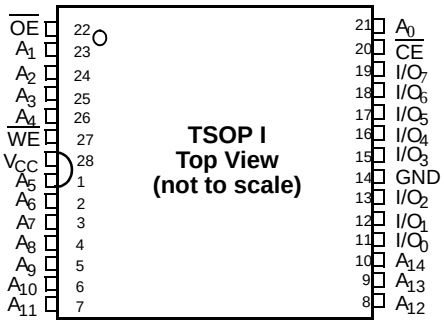
Product Portfolio

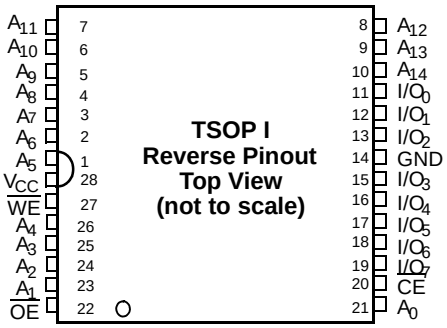
Product	Range	V_{CC} Range (V)			Power Dissipation			
					Operating, I_{CC} (mA)		Standby, I_{SB2} (µA)	
		Min.	Typ.[2]	Max.	Typ.[2]	Max.	Typ.[2]	Max.
CY62256VNLL	Com'l	2.7	3.0	3.6	11	30	0.1	5
CY62256VNLL	Ind'l	2.7	3.0	3.6	11	30	0.1	10
CY62256VNLL	Automotive-A	2.7	3.0	3.6	11	30	0.1	10
CY62256VNLL	Automotive-E	2.7	3.0	3.6	11	30	0.1	130

Pin Configurations

Narrow SOIC
Top View







Pin Definitions

Pin Number	Type	Description
1–10, 21, 23–26	Input	**A_0–A_{14}**. Address Inputs
11–13, 15–19	Input/Output	**I/O_0–I/O_7**. Data lines. Used as input or output lines depending on operation
27	Input/Control	**$\overline{WE}$**. When selected LOW, a WRITE is conducted. When selected HIGH, a READ is conducted
20	Input/Control	**$\overline{CE}$**. When LOW, selects the chip. When HIGH, deselects the chip
22	Input/Control	**$\overline{OE}$**. Output Enable. Controls the direction of the I/O pins. When LOW, the I/O pins behave as outputs. When deasserted HIGH, I/O pins are tri-stated, and act as input data pins
14	Ground	**GND**. Ground for the device
28	Power Supply	**V_{CC}**. Power supply for the device

Note:
2. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC} Typ., T_A = 25°C, and t_{AA} = 70 ns.

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature .....–65°C to + 150°C

Ambient Temperature with Power Applied.....–55°C to + 125°C

Supply Voltage to Ground Potential (Pin 28 to Pin 14) ..... –0.5V to + 4.6V

DC Voltage Applied to Outputs in High-Z State[3] .....–0.5V to V_{CC} + 0.5V

DC Input Voltage[3].....–0.5V to V_{CC} + 0.5V

Output Current into Outputs (LOW) .....20 mA

Static Discharge Voltage..... > 2001V (per MIL-STD-883, Method 3015)

Latch-up Current..... > 200 mA

Operating Range

Device	Range	Ambient Temperature (T_A)[4]	V_{CC}
CY62256VN	Commercial	0°C to +70°C	2.7V to 3.6V
	Industrial	–40°C to +85°C	
	Automotive-A	–40°C to +85°C	
	Automotive-E	–40°C to +125°C	

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		-70			Unit
				Min.	Typ.[2]	Max.	
V_{OH}	Output HIGH Voltage	I_{OH} = –1.0 mA	V_{CC} = 2.7V	2.4			V
V_{OL}	Output LOW Voltage	I_{OL} = 2.1 mA	V_{CC} = 2.7V			0.4	V
V_{IH}	Input HIGH Voltage			2.2		V_{CC} + 0.3V	V
V_{IL}	Input Leakage Voltage			–0.5		0.8	V
I_{IX}	Input Leakage Current	GND ≤ V_{IN} ≤ V_{CC}	Com'l/Ind'l/Auto-A	–1		+1	µA
			Auto-E	–10		+10	µA
I_{OZ}	Output Leakage Current	GND ≤ V_{IN} ≤ V_{CC}, Output Disabled	Com'l/Ind'l/Auto-A	–1		+1	µA
			Auto-E	–10		+10	µA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = 3.6V, I_{OUT} = 0 mA, f = f_{MAX} = $1/t_{RC}$	All Ranges		11	30	mA
I_{SB1}	Automatic CE Power down Current - TTL Inputs	V_{CC} = 3.6V, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}	All Ranges		100	300	µA
I_{SB2}	Automatic CE Power-down Current- CMOS Inputs	V_{CC} = 3.6V, $\overline{CE}$ ≥ V_{CC} – 0.3V V_{IN} ≥ V_{CC} – 0.3V or V_{IN} ≤ 0.3V, f = 0	Com'l		0.1	5	µA
			Ind'l/Auto-A			10	
			Auto-E			130	

Notes:
3. V_{IL} (min.) = –2.0V for pulse durations of less than 20 ns.
4. T_A is the "Instant-On" case temperature

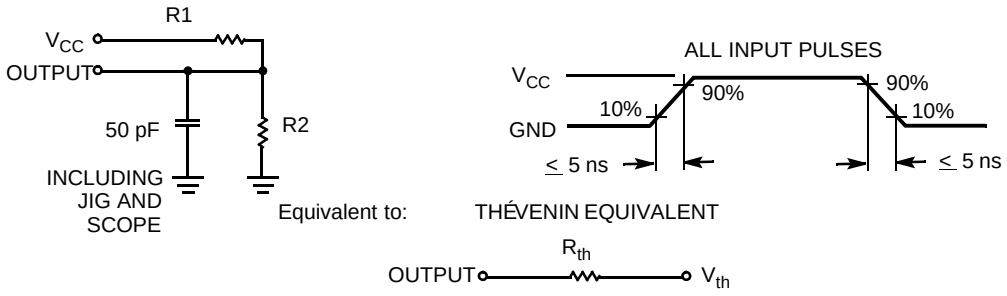
Capacitance[5]

Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	T_A = 25°C, f = 1 MHz, V_{CC} = 3.0V	6	pF
C_{OUT}	Output Capacitance		8	pF

Thermal Resistance[5]

Parameter	Description	Test Conditions	SOIC	TSOPI	RTSOPI	Unit
Θ_{JA}	Thermal Resistance (Junction to Ambient)	Still Air, soldered on a 3 × 4.5 inch, two-layer printed circuit board	68.45	87.62	87.62	°C/W
Θ_{JC}	Thermal Resistance (Junction to Case)		26.94	23.73	23.73	°C/W

AC Test Loads and Waveforms

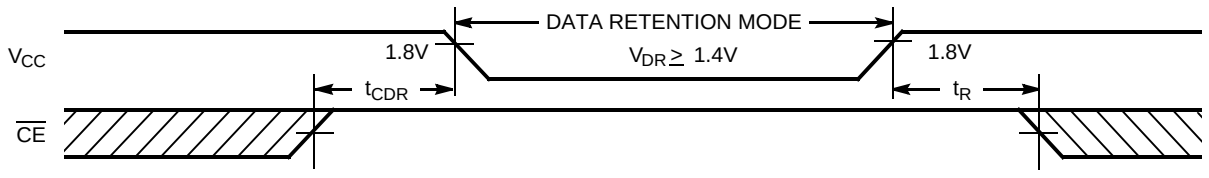


Parameter	Value	Units
R1	1100	Ohms
R2	1500	Ohms
RTH	645	Ohms
VTH	1.750	Volts

Data Retention Characteristics (Over the Operating Range)

Parameter	Description	Conditions[6]		Min.	Typ.[2]	Max.	Unit
V_{DR}	V_{CC} for Data Retention			1.4			V
I_{CCDR}	Data Retention Current	$\overline{V_{CC}}$ = 1.4V, $\overline{CE} \geq V_{CC} - 0.3V$, $V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} \leq 0.3V$	Com'l		0.1	3	µA
			Ind'l/Auto-A			6	
			Auto-E			50	
t_{CDR}[6]	Chip Deselect to Data Retention Time			0			ns
t_R[5]	Operation Recovery Time			t_{RC}			ns

Data Retention Waveform



Note:
5. Tested initially and after any design or process changes that may affect these parameters.
6. No input may exceed V_{CC} + 0.3V.

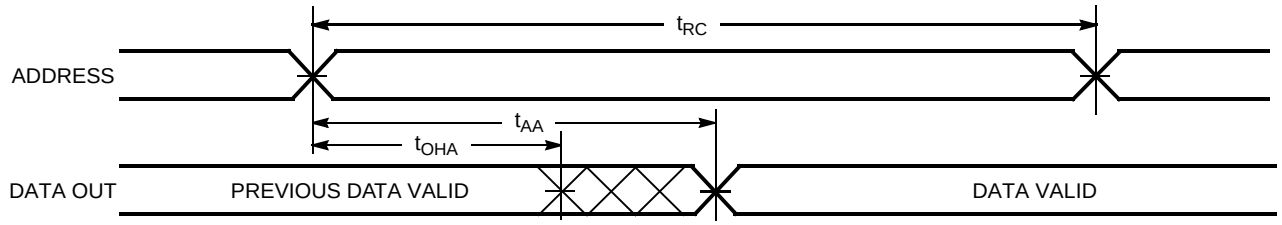
Switching Characteristics Over the Operating Range[7]

Parameter	Description	CY62256VN-70		Unit
		Min.	Max.	
Read Cycle				
t_{RC}	Read Cycle Time	70		ns
t_{AA}	Address to Data Valid		70	ns
t_{OHA}	Data Hold from Address Change	10		ns
t_{ACE}	$\overline{CE}$ LOW to Data Valid		70	ns
t_{DOE}	$\overline{OE}$ LOW to Data Valid		35	ns
t_{LZOE}	$\overline{OE}$ LOW to Low-Z[8]	5		ns
t_{HZOE}	$\overline{OE}$ HIGH to High-Z[8, 9]		25	ns
t_{LZCE}	$\overline{CE}$ LOW to Low-Z[8]	10		ns
t_{HZCE}	$\overline{CE}$ HIGH to High-Z[8, 9]		25	ns
t_{PU}	$\overline{CE}$ LOW to Power-up	0		ns
t_{PD}	$\overline{CE}$ HIGH to Power-down		70	ns
Write Cycle[10, 11]				
t_{WC}	Write Cycle Time	70		ns
t_{SCE}	$\overline{CE}$ LOW to Write End	60		ns
t_{AW}	Address Set-up to Write End	60		ns
t_{HA}	Address Hold from Write End	0		ns
t_{SA}	Address Set-up to Write Start	0		ns
t_{PWE}	$\overline{WE}$ Pulse Width	50		ns
t_{SD}	Data Set-up to Write End	30		ns
t_{HD}	Data Hold from Write End	0		ns
t_{HZWE}	$\overline{WE}$ LOW to High-Z[8, 9]		25	ns
t_{LZWE}	$\overline{WE}$ HIGH to Low-Z[8]	10		ns

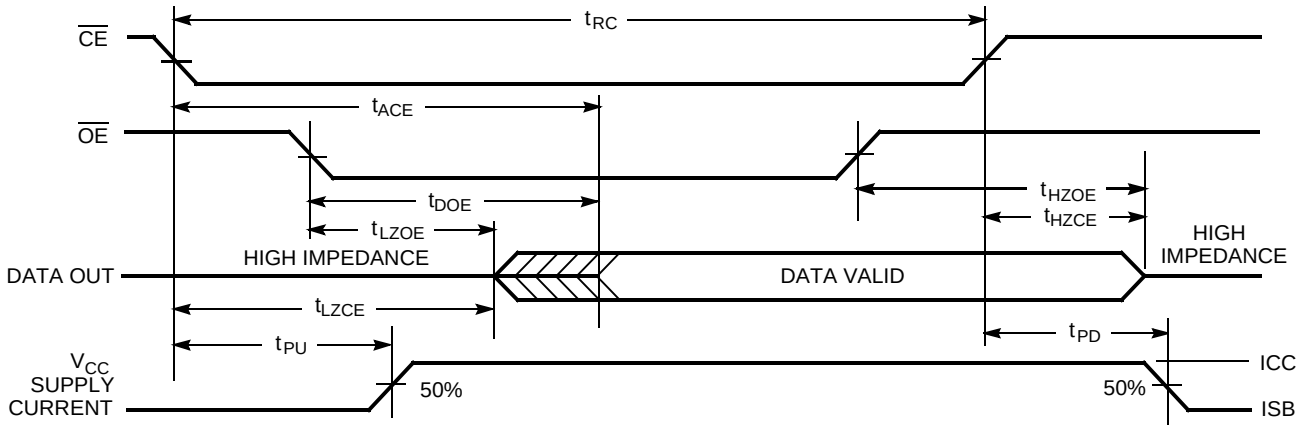
Notes:
7. Test conditions assume signal transition time of 5 ns or less timing reference levels of $V_{CC}/2$, input pulse levels of 0 to V_{CC}, and output loading of the specified I_{OL}/I_{OH} and 100-pF load capacitance.
8. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
9. t_{HZOE}, t_{HZCE}, and t_{HZWE} are specified with C_L = 5 pF as in (b) of AC Test Loads. Transition is measured ± 200 mV from steady-state voltage.
10. The internal write time of the memory is defined by the overlap of $\overline{CE}$ LOW and $\overline{WE}$ LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
11. The minimum write cycle time for write cycle #3 ($\overline{WE}$ controlled, $\overline{OE}$ LOW) is the sum of t_{HZWE} and t_{SD}.

Switching Waveforms

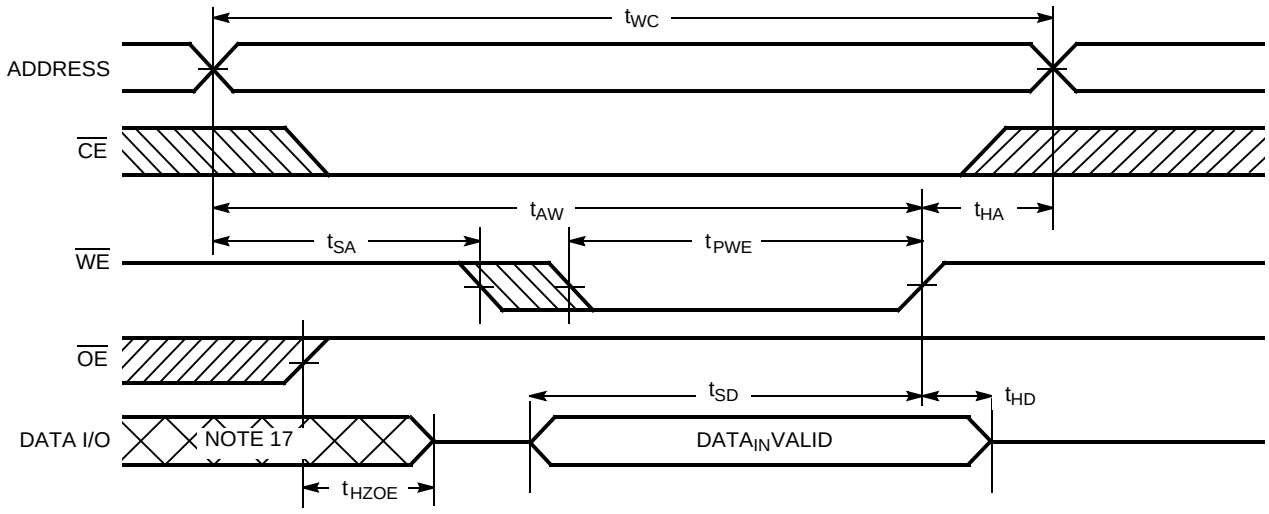
Read Cycle No. 1[12, 13]



Read Cycle No. 2[13, 14]



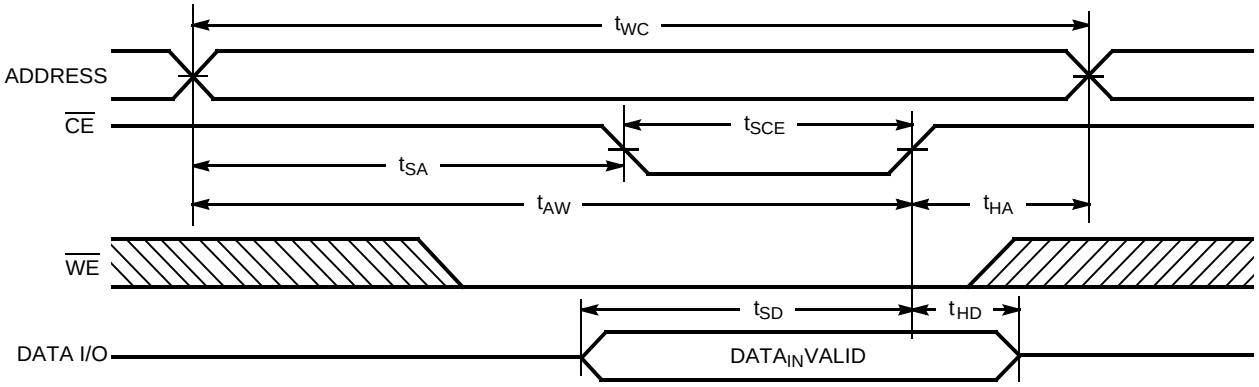
Write Cycle No. 1 (WE Controlled)[10, 15, 16]



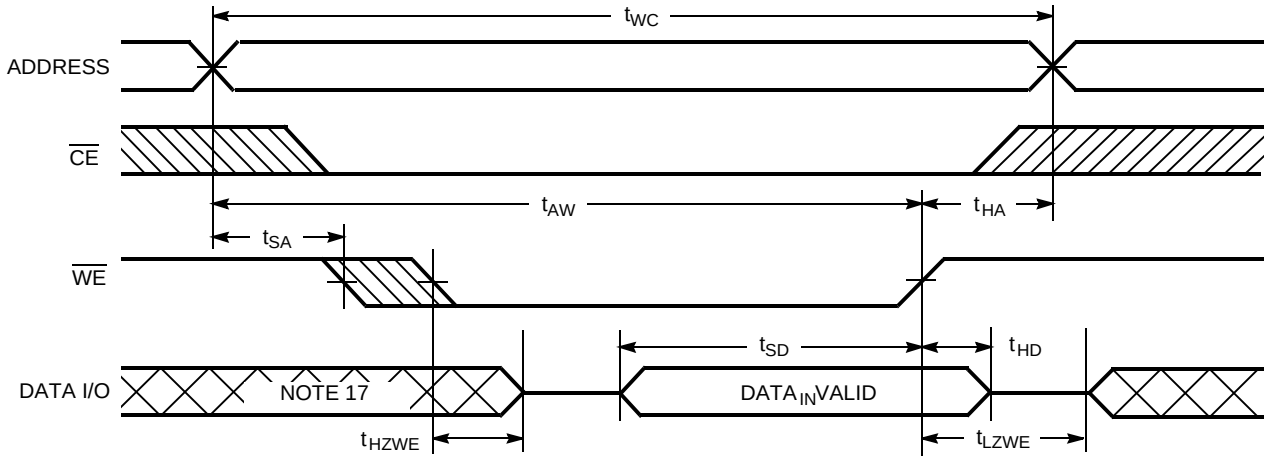
Notes:
12. Device is continuously selected. $\overline{OE}$, $\overline{CE}$ = V_{IL}.
13. $\overline{WE}$ is HIGH for read cycle.
14. Address valid prior to or coincident with $\overline{CE}$ transition LOW.
15. Data I/O is high impedance if $\overline{OE}$ = V_{IH}.
16. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ HIGH, the output remains in a high-impedance state.
17. During this period, the I/Os are in output state and input signals should not be applied.

Switching Waveforms (continued)

Write Cycle No. 2 ($\overline{CE}$ Controlled)[10, 15, 16]

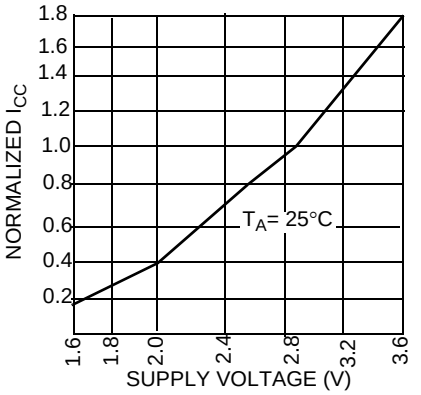


Write Cycle No. 3 ($\overline{WE}$ Controlled, $\overline{OE}$ LOW)[11, 16]

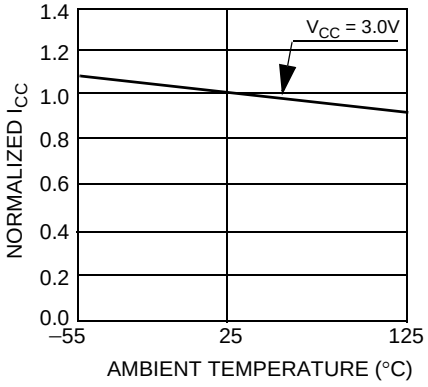


Typical DC and AC Characteristics

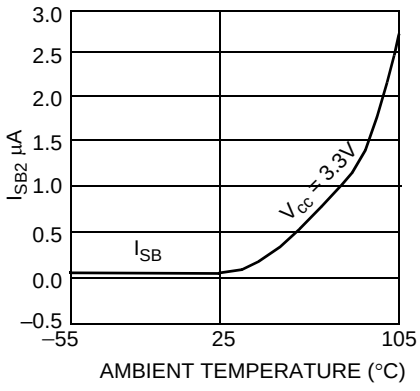
NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



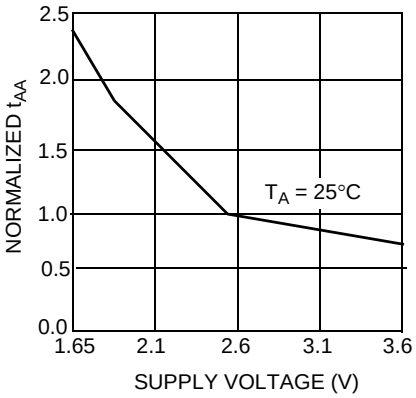
NORMALIZED SUPPLY CURRENT vs. AMBIENT TEMPERATURE



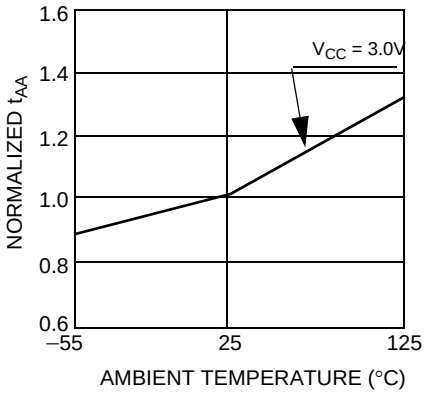
STANDBY CURRENT vs. AMBIENT TEMPERATURE



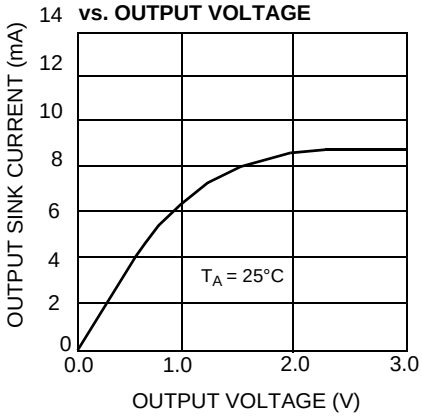
NORMALIZED ACCESS TIME vs. SUPPLY VOLTAGE



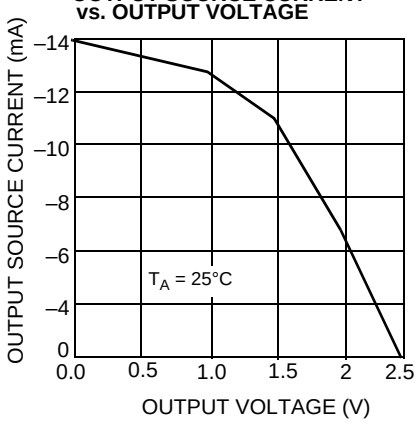
NORMALIZED ACCESS TIME vs. AMBIENT TEMPERATURE



OUTPUT SINK CURRENT vs. OUTPUT VOLTAGE

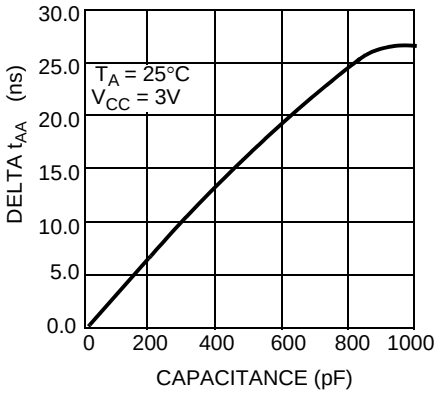


OUTPUT SOURCE CURRENT vs. OUTPUT VOLTAGE

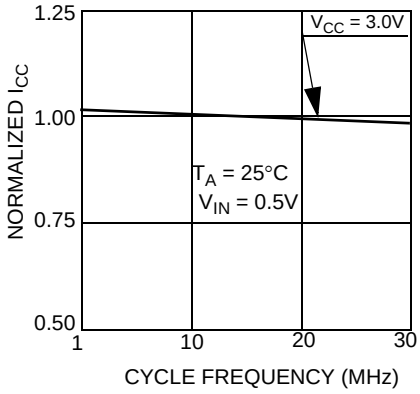


Typical DC and AC Characteristics (continued)

TYPICAL ACCESS TIME CHANGE vs. OUTPUT LOADING



NORMALIZED I_{CC} vs. CYCLE TIME



Truth Table

$\overline{CE}$	$\overline{WE}$	$\overline{OE}$	Inputs/Outputs	Mode	Power
H	X	X	High-Z	Deselect/Power-down	Standby (I_{SB})
L	H	L	Data Out	Read	Active (I_{CC})
L	L	X	Data In	Write	Active (I_{CC})
L	H	H	High-Z	Deselect, Output Disabled	Active (I_{CC})

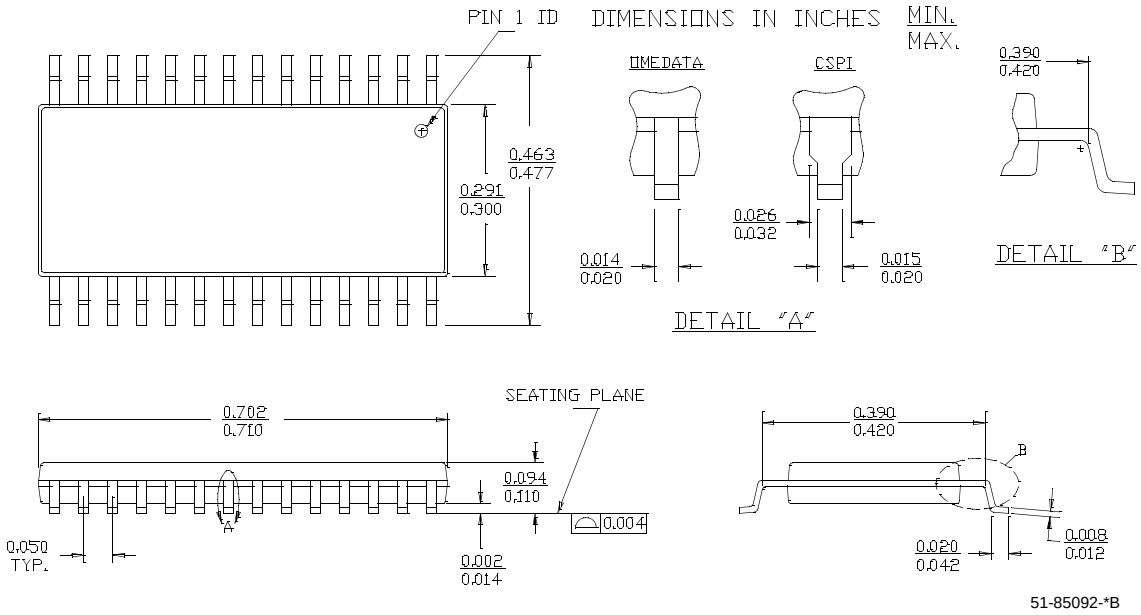
Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
70	CY62256VNLL-70SNC	51-85092	28-lead (300-mil) Narrow SOIC	Commercial
	CY62256VNLL-70SNXC		28-lead (300-mil) Narrow SOIC (Pb-Free)	
	CY62256VNLL-70ZC	51-85071	28-lead TSOP I	
	CY62256VNLL-70ZXC		28-lead TSOP I (Pb-Free)	
	CY62256VNLL-70SNXI	51-85092	28-lead (300-mil) Narrow SOIC (Pb-Free)	Industrial
	CY62256VNLL-70ZI	51-85071	28-lead TSOP I	
	CY62256VNLL-70ZXI		28-lead TSOP I (Pb-Free)	
	CY62256VNLL-70ZRI	51-85074	28-lead Reverse TSOP I	
	CY62256VNLL-70ZRXI		28-lead Reverse TSOP I (Pb-Free)	
	CY62256VNLL-70ZXA	51-85071	28-lead TSOP I (Pb-Free)	Automotive-A
	CY62256VNLL-70SNXE	51-85092	28-lead (300-mil) Narrow SOIC (Pb-Free)	Automotive-E
	CY62256VNLL-70ZXE	51-85071	28-lead TSOP I (Pb-Free)	
	CY62256VNLL-70ZRXE	51-85074	28-lead Reverse TSOP I (Pb-Free)	

Please contact your local Cypress sales representative for availability of other parts

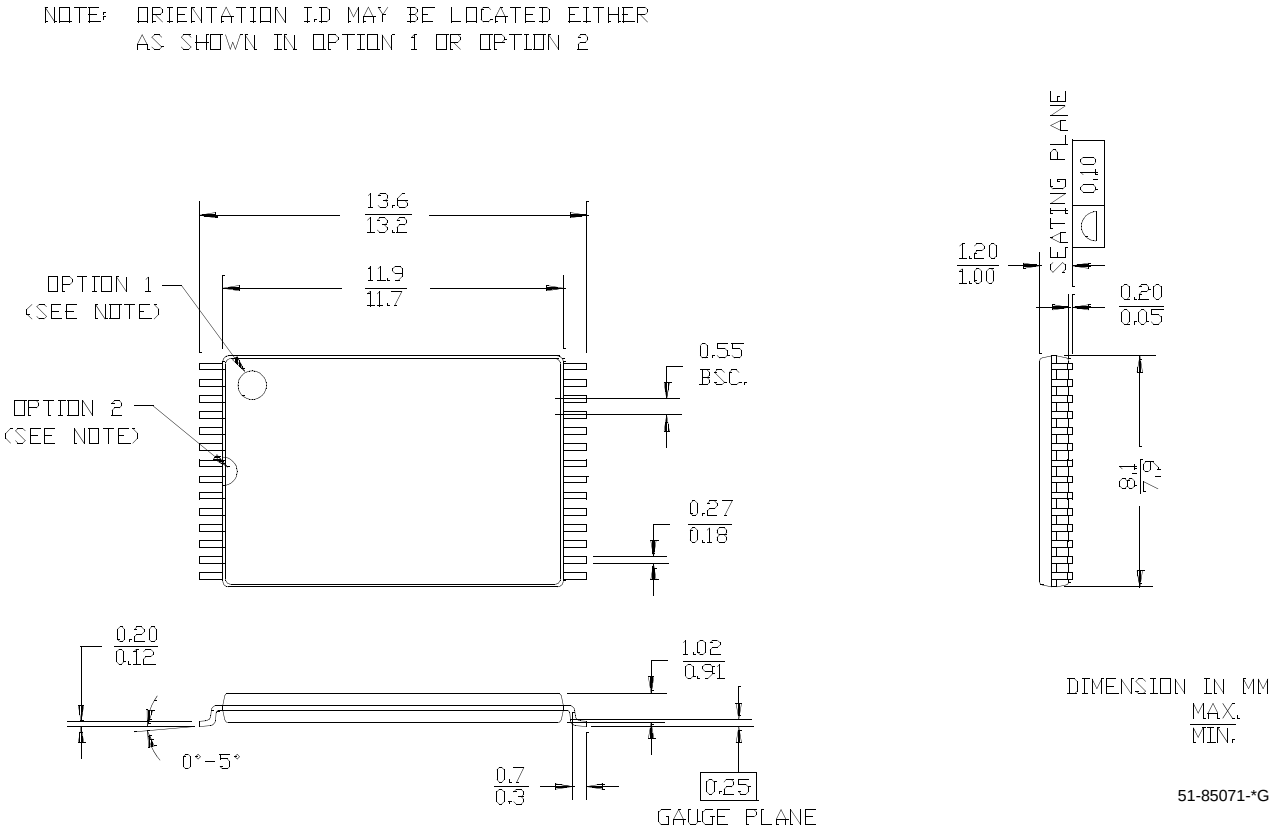
Package Diagrams

28-lead (300-mil) SNC (Narrow Body) (51-85092)



51-85092-*B

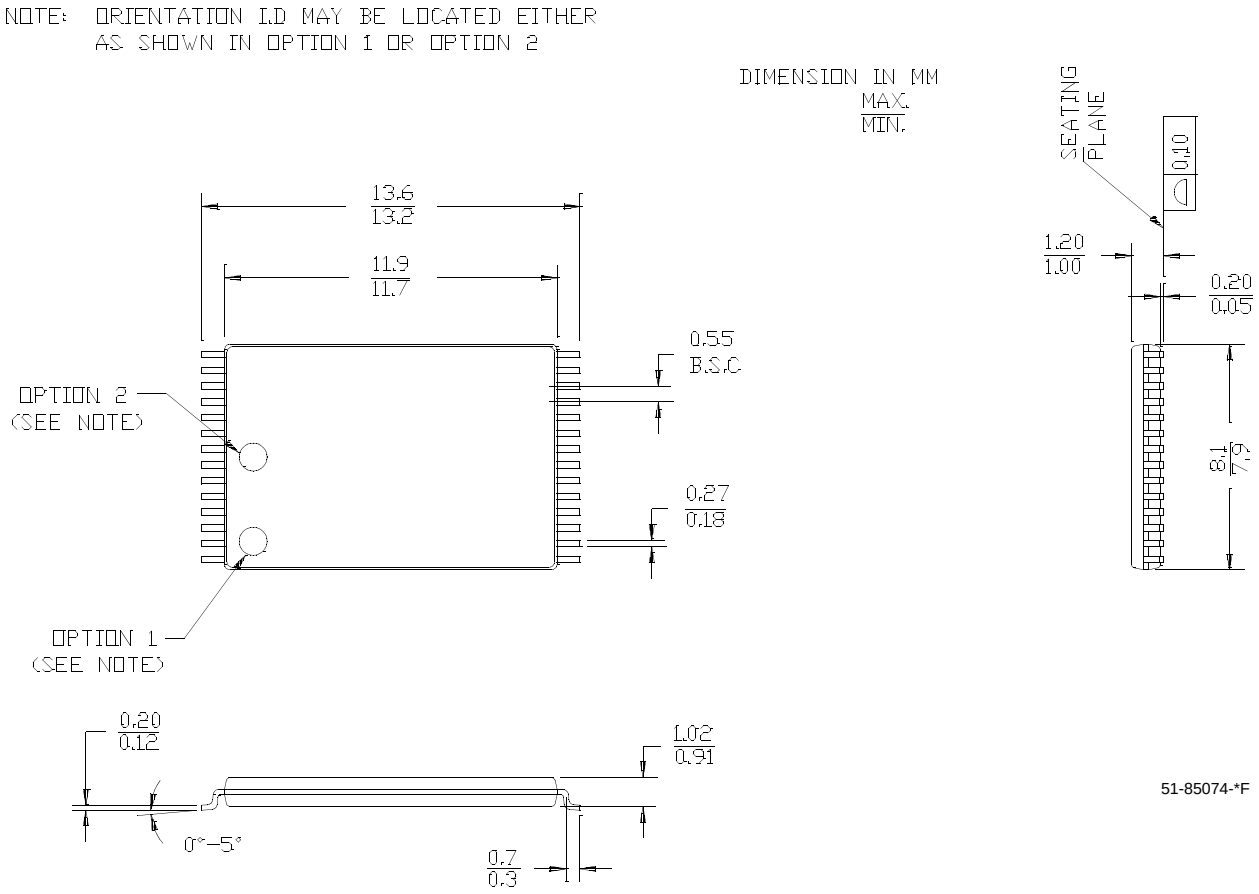
28-lead TSOP 1 (8 × 13.4 mm) (51-85071)



51-85071-*G

Package Diagrams (continued)

28-lead Reverse TSOP 1 (8 × 13.4 mm) (51-85074)



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Document History Page

Document Title: CY62256VN 256K (32K x 8) Static RAM Document Number: 001-06512				
REV.	**ECN NO.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	426504	See ECN	NXR	New Data Sheet
*A	488954	See ECN	NXR	Added Automotive product Updated ordering Information table